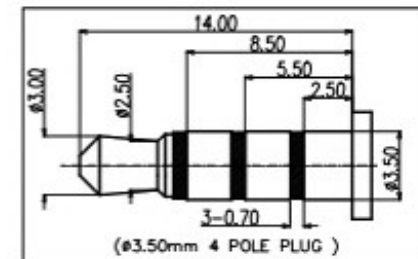
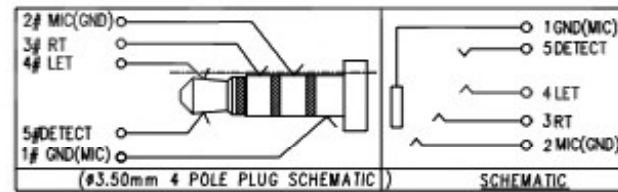
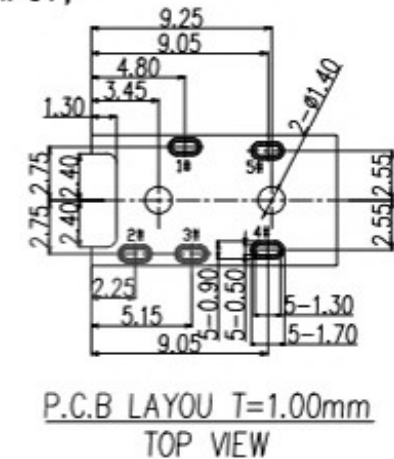
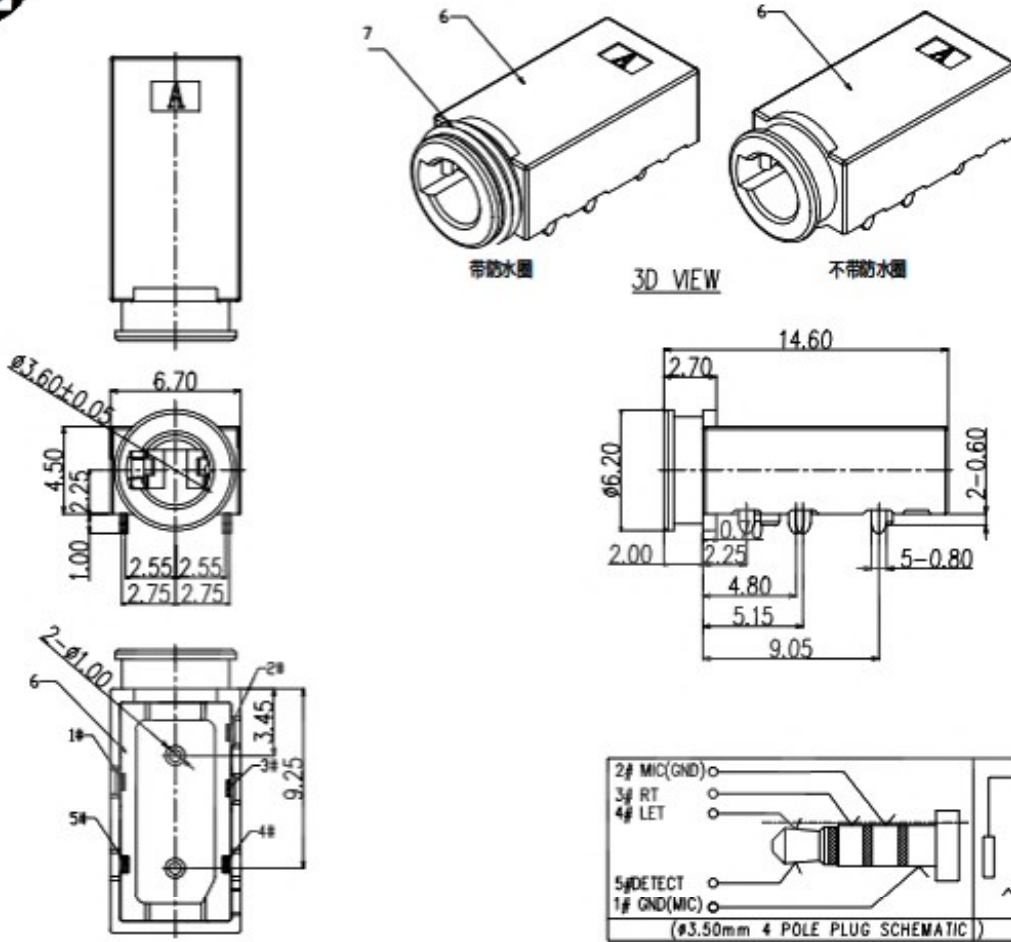


- CONTACT CURRENT RATING: 1A.
- CONTACT RESISTANCE: 100 mΩ MAX.;
- INSULATION RESISTANCE: 100MΩ MIN.;
- DIELECTRIC WITHSTANDING: 500V AC MIN.;
- DURABILITY: 5,000 CYCLES MIN.;
- CONNECTOR MATING FORCES: 30N MAX.;
- CONNECTOR UNMATING FORCES: 3N MIN.;
- TERPROOF LEVEL: IP67;



| | | | | |
|------|-----------------|-----|--|----------|
| 7 | WATERPROOF RING | 1 | SILICA GEL | |
| 6 | HOUSING | 1 | HIGH TEMPERATURE PLASTIC MATERIAL; COLOR BLACK | |
| 5 | TERMINAL 5# | 1 | STAINLESS STEEL; NICKEL UNDER PLATING OVERALL GOLD FLASH PLATING ON SOLDER AREA GOLD FLASH PLATING ON CONTACT AREA | T=0.20mm |
| 4 | TERMINAL 4# | 1 | STAINLESS STEEL; NICKEL UNDER PLATING OVERALL GOLD FLASH PLATING ON SOLDER AREA GOLD FLASH PLATING ON CONTACT AREA | T=0.20mm |
| 3 | TERMINAL 3# | 1 | PHOSPHOR BRONZE; NICKEL UNDER PLATING OVERALL GOLD FLASH PLATING ON SOLDER AREA GOLD FLASH PLATING ON CONTACT AREA | T=0.20mm |
| 2 | TERMINAL 2# | 1 | PHOSPHOR BRONZE; NICKEL UNDER PLATING OVERALL GOLD FLASH PLATING ON SOLDER AREA GOLD FLASH PLATING ON CONTACT AREA | T=0.20mm |
| 1 | TERMINAL 1# | 1 | STAINLESS STEEL; NICKEL UNDER PLATING OVERALL GOLD FLASH PLATING ON SOLDER AREA GOLD FLASH PLATING ON CONTACT AREA | T=0.20mm |
| ITEM | NAME | QTY | DESCRIPTION | NOTE |

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|-----------|----|------------------------|--------------|---------|-------|-----------|--|---------|------|--------|--|
| PART NAME | | PHONE JACK | | DRAWING | | Y.C,ZHANG | | DWG.No. | | SBICL | |
| PART NO. | | PJ-380-C | | CHECK | | G.C.Chen | | REV. | | A1 | |
| UNIT : | mm | TOLERANCE OTHERWISE | UP TO 5 | ±0.2 | ANGLE | APPROVAL | | DATE | PAGE | 1 OF 1 | |
| | | | ABOVE 5 ~ 30 | ±0.3 | | | | | | | |
| | | | ABOVE 30 | ±0.5 | | | | | | | |
| | | | ANGLE | ±3' | | | | | | | |
| | | | | SCALE | | 2:1 | | | | | |